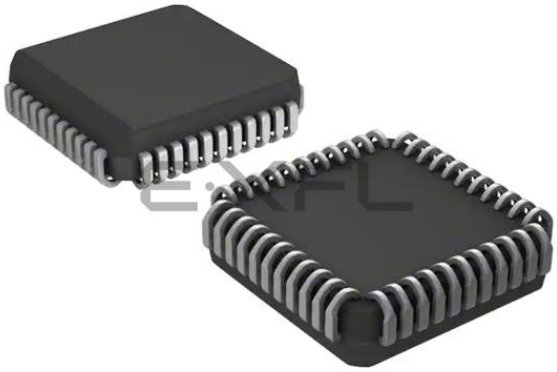

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

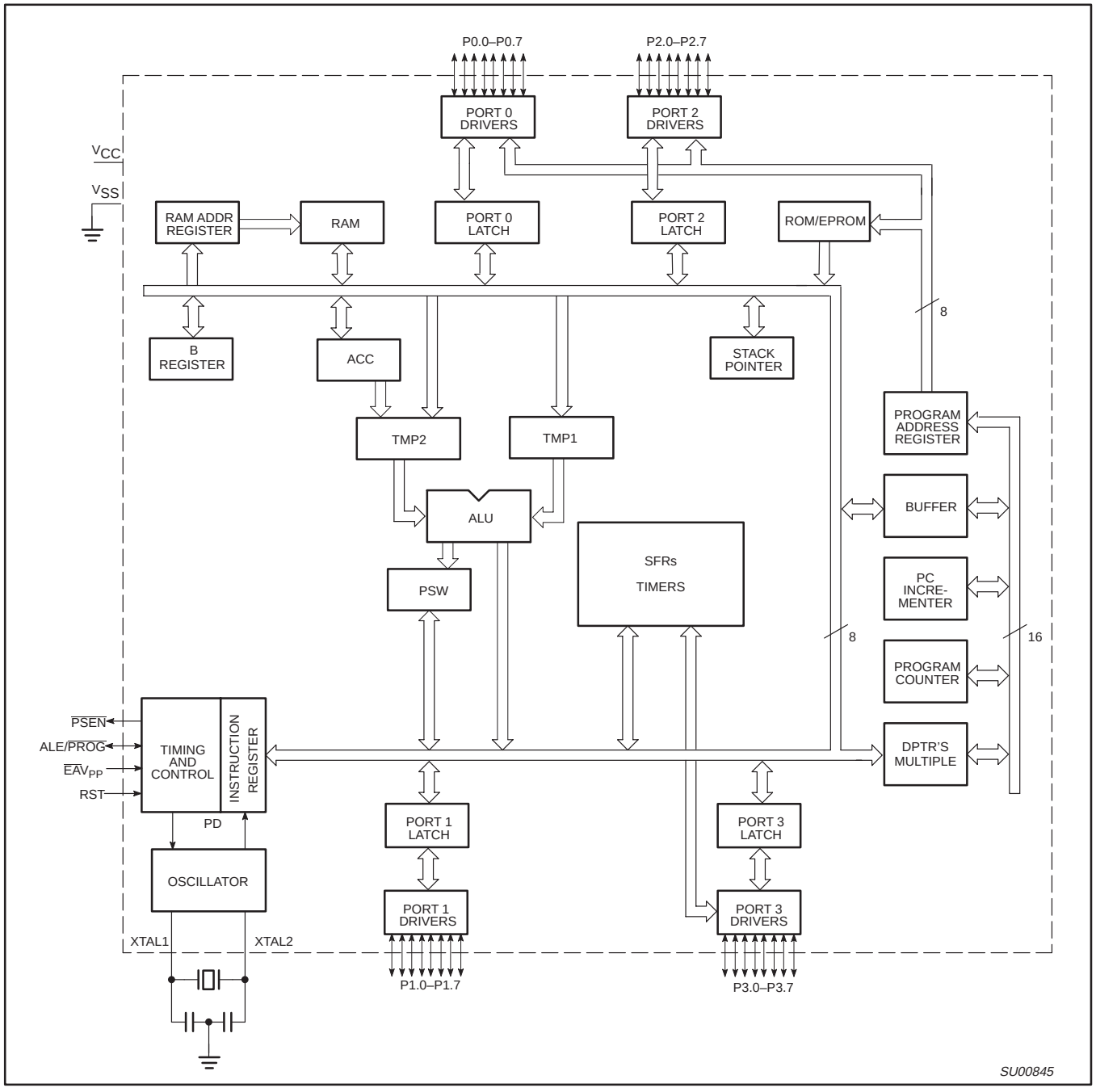
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	16MHz
Connectivity	EBI/EMI, UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p87c52sbaa-512

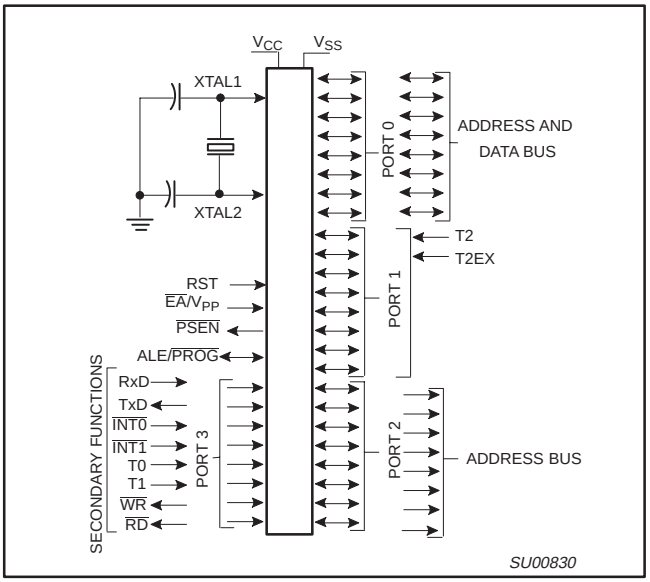
80C52/87C52 ORDERING INFORMATION

	MEMORY SIZE 8K × 8	TEMPERATURE RANGE °C AND PACKAGE	VOLTAGE RANGE	FREQ. (MHz)	DWG. #
ROM	P80C52SBPN	0 to +70, Plastic Dual In-line Package	2.7 V to 5.5 V	0 to 16	SOT129-1
OTP	P87C52SBPN				
ROM	P80C52SBAA	0 to +70, Plastic Leaded Chip Carrier	2.7 V to 5.5 V	0 to 16	SOT187-2
OTP	P87C52SBAA				
ROM	P80C52SBBB	0 to +70, Plastic Quad Flat Pack	2.7 V to 5.5 V	0 to 16	SOT307-2
OTP	P87C52SBBB				
ROM	P80C52SFPN	–40 to +85, Plastic Dual In-line Package	2.7 V to 5.5 V	0 to 16	SOT129-1
OTP	P87C52SFPN				
ROM	P80C52SFAA	–40 to +85, Plastic Leaded Chip Carrier	2.7 V to 5.5 V	0 to 16	SOT187-2
OTP	P87C52SFAA				
ROM	P80C52SFBB	–40 to +85, Plastic Quad Flat Pack	2.7 V to 5.5 V	0 to 16	SOT307-2
OTP	P87C52SFBB				
ROM	P80C52UBAA	0 to +70, Plastic Leaded Chip Carrier	5 V	0 to 33	SOT187-2
OTP	P87C52UBAA				
ROM	P80C52UBPN	0 to +70, Plastic Dual In-line Package	5 V	0 to 33	SOT129-1
OTP	P87C52UBPN				
ROM	P80C52UFAA	–40 to +85, Plastic Leaded Chip Carrier	5 V	0 to 33	SOT187-2
OTP	P87C52UFAA				

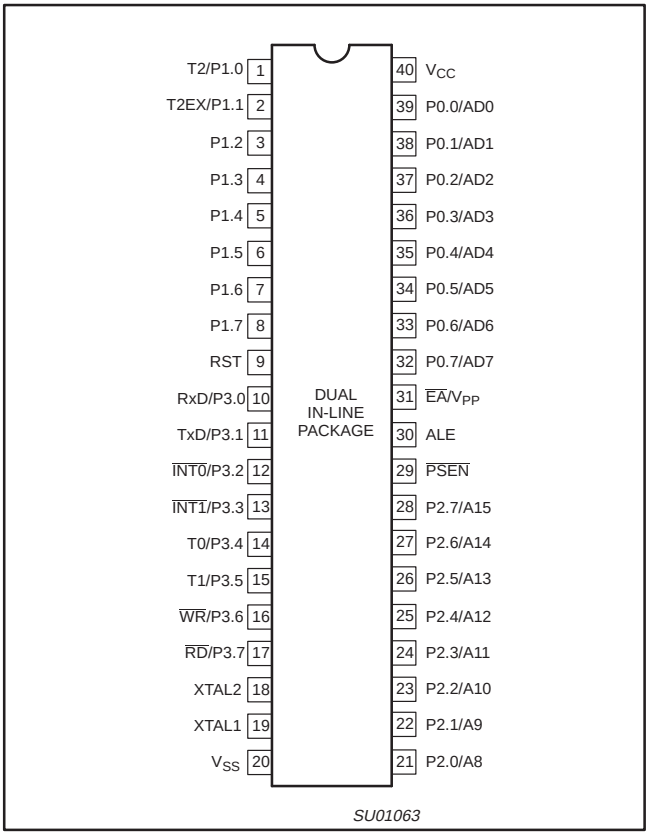
BLOCK DIAGRAM



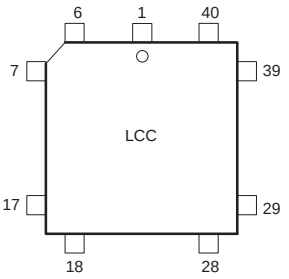
LOGIC SYMBOL



PIN CONFIGURATIONS



PLASTIC LEADED CHIP CARRIER PIN FUNCTIONS

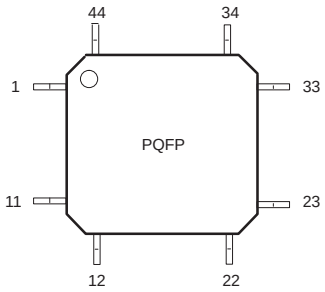


Pin	Function	Pin	Function	Pin	Function
1	NIC*	16	P3.4/T0	31	P2.7/A15
2	P1.0/T2	17	P3.5/T1	32	PSEN
3	P1.1/T2EX	18	P3.6/WR	33	ALE
4	P1.2	19	P3.7/RD	34	NIC*
5	P1.3	20	XTAL2	35	EA/VPP
6	P1.4	21	XTAL1	36	P0.7/AD7
7	P1.5	22	VSS	37	P0.6/AD6
8	P1.6	23	NIC*	38	P0.5/AD5
9	P1.7	24	P2.0/A8	39	P0.4/AD4
10	RST	25	P2.1/A9	40	P0.3/AD3
11	P3.0/RxD	26	P2.2/A10	41	P0.2/AD2
12	NIC*	27	P2.3/A11	42	P0.1/AD1
13	P3.1/TxD	28	P2.4/A12	43	P0.0/AD0
14	P3.2/INT0	29	P2.5/A13	44	VCC
15	P3.3/INT1	30	P2.6/A14		

* NO INTERNAL CONNECTION

SU01062

PLASTIC QUAD FLAT PACK PIN FUNCTIONS



Pin	Function	Pin	Function	Pin	Function
1	P1.5	16	VSS	31	P0.6/AD6
2	P1.6	17	NIC*	32	P0.5/AD5
3	P1.7	18	P2.0/A8	33	P0.4/AD4
4	RST	19	P2.1/A9	34	P0.3/AD3
5	P3.0/RxD	20	P2.2/A10	35	P0.2/AD2
6	NIC*	21	P2.3/A11	36	P0.1/AD1
7	P3.1/TxD	22	P2.4/A12	37	P0.0/AD0
8	P3.2/INT0	23	P2.5/A13	38	VCC
9	P3.3/INT1	24	P2.6/A14	39	NIC*
10	P3.4/T0	25	P2.7/A15	40	P1.0/T2
11	P3.5/T1	26	PSEN	41	P1.1/T2EX
12	P3.6/WR	27	ALE	42	P1.2
13	P3.7/RD	28	NIC*	43	P1.3
14	XTAL2	29	EA/VPP	44	P1.4
15	XTAL1	30	P0.7/AD7		

* NO INTERNAL CONNECTION

SU01064

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator, as shown in the logic symbol.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

Reset

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-up reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles.

Stop Clock Mode

The static design enables the clock speed to be reduced down to 0 MHz (stopped). When the oscillator is stopped, the RAM and Special Function Registers retain their values. This mode allows step-by-step utilization and permits reduced system power consumption by lowering the clock frequency down to any value. For lowest power consumption the Power Down mode is suggested.

Idle Mode

In idle mode (see Table 2), the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

Power-Down Mode

To save even more power, a Power Down mode (see Table 2) can be invoked by software. In this mode, the oscillator is stopped and the instruction that invoked Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values down to 2.0 V and care must be taken to return V_{CC} to the minimum specified operating voltages before the Power Down Mode is terminated.

For the 87C51 and 80C51 either a hardware reset or external interrupt can be used to exit from Power Down. Reset redefines all the SFRs but does not change the on-chip RAM. An external interrupt allows both the SFRs and the on-chip RAM to retain their values. WUPD (AUXR1.3–Wakeup from Power Down) enables or disables the wakeup from power down with external interrupt. Where:

WUPD = 0 Disable
WUPD = 1 Enable

To properly terminate Power Down the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize (normally less than 10 ms).

With an external interrupt, INT0 or INT1 must be enabled and configured as level-sensitive. Holding the pin low restarts the oscillator but bringing the pin back high completes the exit. Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put the device into Power Down.

LPEP

The eprom array contains some analog circuits that are not required when V_{CC} is less than 4 V, but are required for a V_{CC} greater than 4 V. The LPEP bit (AUXR.4), when set, will powerdown these analog circuits resulting in a reduced supply current. This bit should be set ONLY for applications that operate at a V_{CC} less than 4 V.

Design Consideration

- When the idle mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

ONCE™ Mode

The ONCE (“On-Circuit Emulation”) Mode facilitates testing and debugging of systems without the device having to be removed from the circuit. The ONCE Mode is invoked by:

1. Pull ALE low while the device is in reset and $\overline{\text{PSEN}}$ is high;
2. Hold ALE low as RST is deactivated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and $\overline{\text{PSEN}}$ are weakly pulled high. The oscillator circuit remains active. While the device is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a normal reset is applied.

Table 2. External Pin Status During Idle and Power-Down Modes

MODE	PROGRAM MEMORY	ALE	$\overline{\text{PSEN}}$	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

(MSB)							(LSB)
TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$

Symbol	Position	Name and Significance
TF2	T2CON.7	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK or TCLK = 1.
EXF2	T2CON.6	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	T2CON.5	Receive clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	T2CON.4	Transmit clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	T2CON.3	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	T2CON.2	Start/stop control for Timer 2. A logic 1 starts the timer.
C/$\overline{T2}$	T2CON.1	Timer or counter select. (Timer 2) 0 = Internal timer (OSC/12) 1 = External event counter (falling edge triggered).
CP/$\overline{RL2}$	T2CON.0	Capture/Reload flag. When set, captures will occur on negative transitions at T2EX if EXEN2 = 1. When cleared, auto-reloads will occur either with Timer 2 overflows or negative transitions at T2EX when EXEN2 = 1. When either RCLK = 1 or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

SU00728

Figure 1. Timer/Counter 2 (T2CON) Control Register

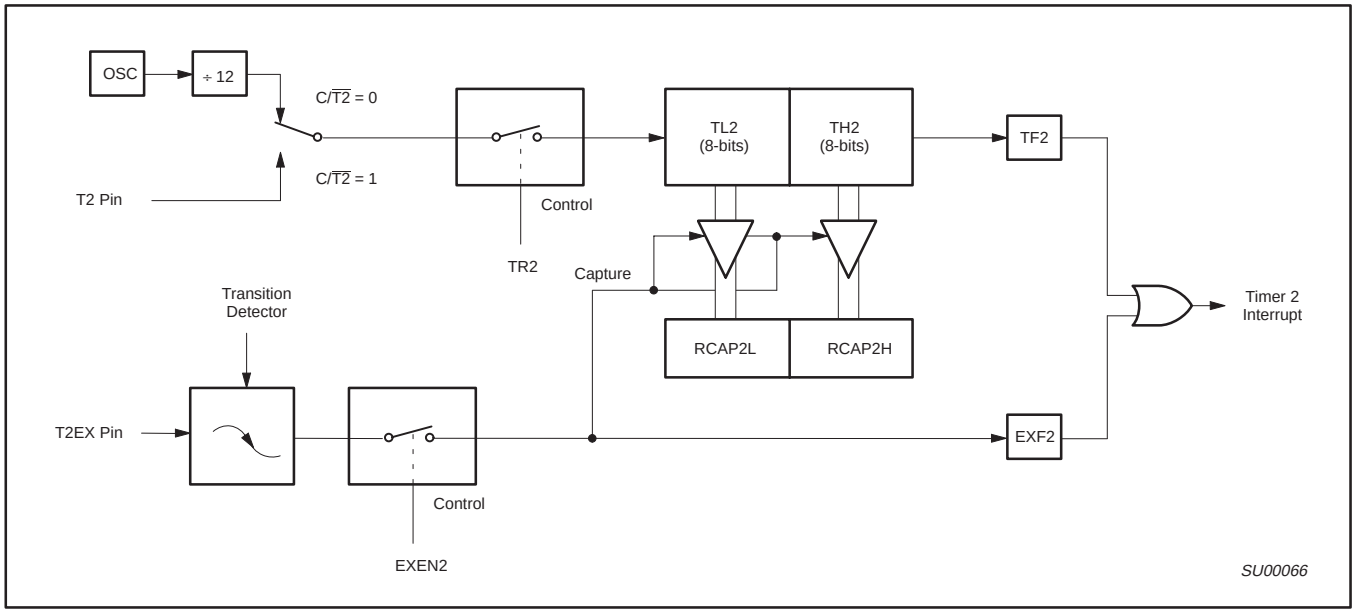


Figure 2. Timer 2 in Capture Mode

T2MOD Address = 0C9H Reset Value = XXXX XX00B

Not Bit Addressable

—	—	—	—	—	—	T2OE	DCEN
Bit 7	6	5	4	3	2	1	0

Symbol	Function
—	Not implemented, reserved for future use.*
T2OE	Timer 2 Output Enable bit.
DCEN	Down Count Enable bit. When set, this allows Timer 2 to be configured as an up/down counter.

* User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU00729

Figure 3. Timer 2 Mode (T2MOD) Control Register

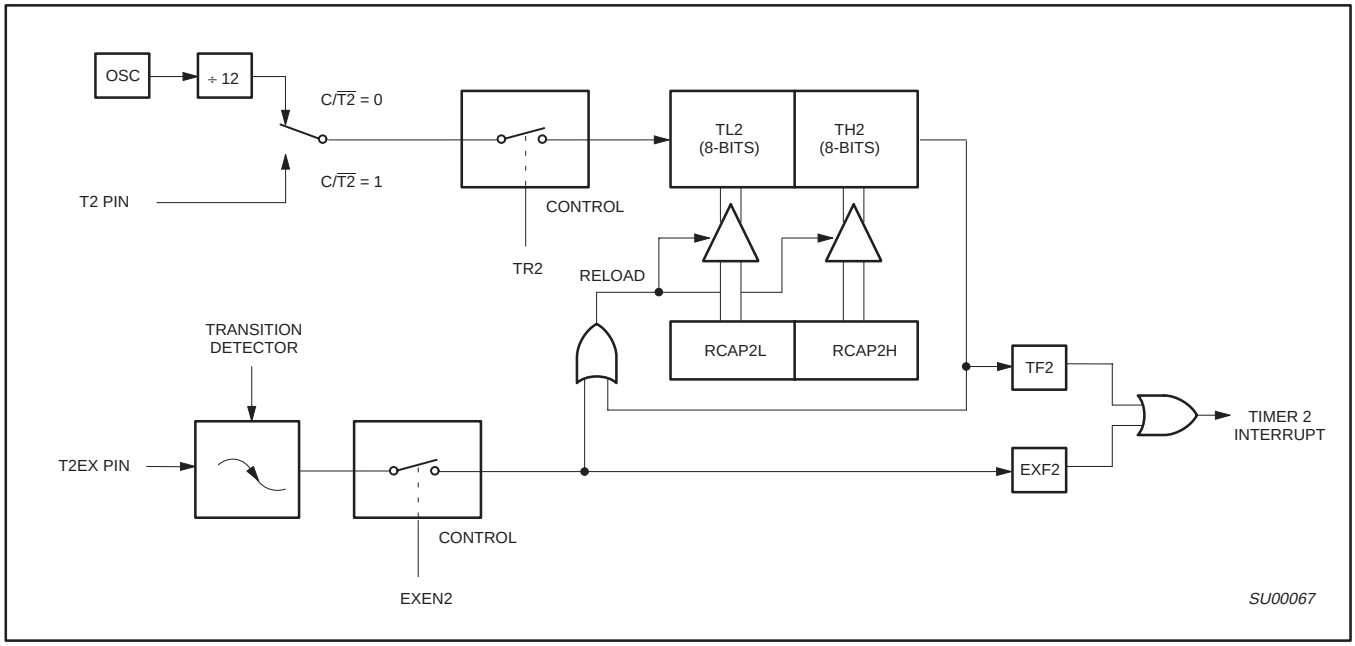


Figure 4. Timer 2 in Auto-Reload Mode (DCEN = 0)

and 1 and exclude Slave 2 use address 1110 0100, since it is necessary to make bit 2 = 1 to exclude slave 2.

The Broadcast Address for each slave is created by taking the logical OR of SADDR and SADEN. Zeros in this result are trended as don't-cares. In most cases, interpreting the don't-cares as ones, the broadcast address will be FF hexadecimal.

Upon reset SADDR (SFR address 0A9H) and SADEN (SFR address 0B9H) are leaded with 0s. This produces a given address of all "don't cares" as well as a Broadcast address of all "don't cares". This effectively disables the Automatic Addressing mode and allows the microcontroller to use standard 80C51 type UART drivers which do not make use of this feature.

SCON Address = 98H — Reset Value = 0000 0000B

Bit Addressable

	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI
Bit:	7	6	5	4	3	2	1	0
	(SMOD0 = 0/1)*							

Symbol	Function
FE	Framing Error bit. This bit is set by the receiver when an invalid stop bit is detected. The FE bit is not cleared by valid frames but should be cleared by software. The SMOD0 bit must be set to enable access to the FE bit.
SM0	Serial Port Mode Bit 0, (SMOD0 must = 0 to access bit SM0)
SM1	Serial Port Mode Bit 1

SM0	SM1	Mode	Description	Baud Rate**
0	0	0	shift register	$f_{OSC}/12$
0	1	1	8-bit UART	variable
1	0	2	9-bit UART	$f_{OSC}/64$ or $f_{OSC}/32$
1	1	3	9-bit UART	variable

SM2	Enables the Automatic Address Recognition feature in Modes 2 or 3. If SM2 = 1 then RI will not be set unless the received 9th data bit (RB8) is 1, indicating an address, and the received byte is a Given or Broadcast Address. In Mode 1, if SM2 = 1 then RI will not be activated unless a valid stop bit was received, and the received byte is a Given or Broadcast Address. In Mode 0, SM2 should be 0.
REN	Enables serial reception. Set by software to enable reception. Clear by software to disable reception.
TB8	The 9th data bit that will be transmitted in Modes 2 and 3. Set or clear by software as desired.
RB8	In modes 2 and 3, the 9th data bit that was received. In Mode 1, if SM2 = 0, RB8 is the stop bit that was received. In Mode 0, RB8 is not used.
TI	Transmit interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission. Must be cleared by software.
RI	Receive interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or halfway through the stop bit time in the other modes, in any serial reception (except see SM2). Must be cleared by software.

NOTE:
*SMOD0 is located at PCON6.
**f_{OSC} = oscillator frequency

SU00043

Figure 7. SCON: Serial Port Control Register

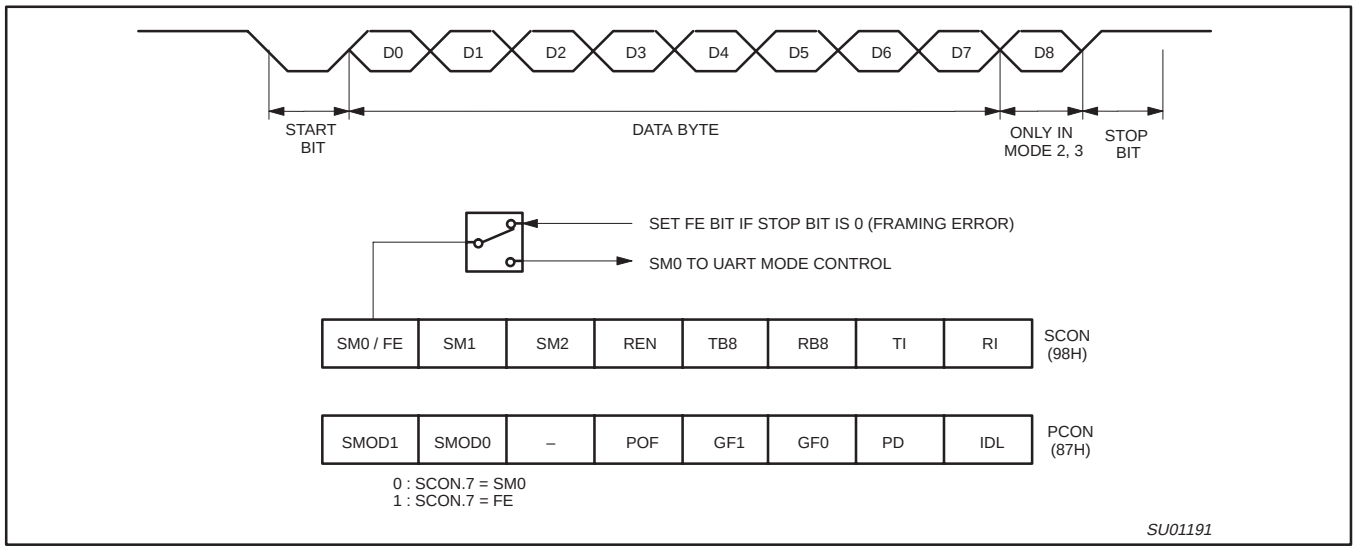


Figure 8. UART Framing Error Detection

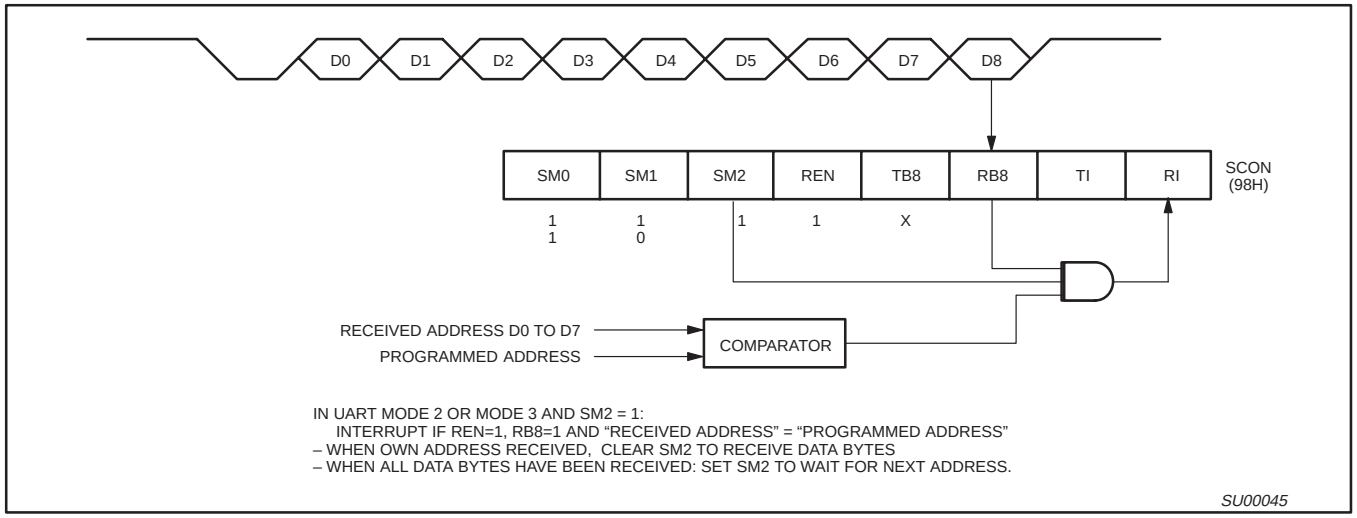


Figure 9. UART Multiprocessor Communication, Automatic Address Recognition

	7	6	5	4	3	2	1	0
IP (0B8H)	—	—	PT2	PS	PT1	PX1	PT0	PX0

Priority Bit = 1 assigns higher priority
Priority Bit = 0 assigns lower priority

BIT	SYMBOL	FUNCTION
IP.7	—	Not implemented, reserved for future use.
IP.6	—	Not implemented, reserved for future use.
IP.5	PT2	Timer 2 interrupt priority bit.
IP.4	PS	Serial Port interrupt priority bit.
IP.3	PT1	Timer 1 interrupt priority bit.
IP.2	PX1	External interrupt 1 priority bit.
IP.1	PT0	Timer 0 interrupt priority bit.
IP.0	PX0	External interrupt 0 priority bit.

SU00572

Figure 11. IP Registers

	7	6	5	4	3	2	1	0
IPH (B7H)	—	—	PT2H	PSH	PT1H	PX1H	PT0H	PX0H

Priority Bit = 1 assigns higher priority
Priority Bit = 0 assigns lower priority

BIT	SYMBOL	FUNCTION
IPH.7	—	Not implemented, reserved for future use.
IPH.6	—	Not implemented, reserved for future use.
IPH.5	PT2H	Timer 2 interrupt priority bit high.
IPH.4	PSH	Serial Port interrupt priority bit high.
IPH.3	PT1H	Timer 1 interrupt priority bit high.
IPH.2	PX1H	External interrupt 1 priority bit high.
IPH.1	PT0H	Timer 0 interrupt priority bit high.
IPH.0	PX0H	External interrupt 0 priority bit high.

SU01058

Figure 12. IPH Registers

ABSOLUTE MAXIMUM RATINGS[1, 2, 3]

PARAMETER	RATING	UNIT
Operating temperature under bias	0 to +70 or –40 to +85	°C
Storage temperature range	–65 to +150	°C
Voltage on $\overline{EA}/V_{PP}$ pin to V_{SS}	0 to +13.0	V
Voltage on any other pin to V_{SS}	–0.5 to +6.5	V
Maximum I_{OL} per I/O pin	15	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.5	W

NOTES:
1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.
3. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C

SYMBOL	FIGURE	PARAMETER	CLOCK FREQUENCY RANGE –f		UNIT
			MIN	MAX	
$1/t_{CLCL}$	29	Oscillator frequency			
		Speed versions : S (16 MHz)	0	16	MHz
		U (33 MHz)	0	33	MHz

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 2.7 V to 5.5 V, V_{SS} = 0 V (16 MHz devices)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage[11]	4.0 V < V_{CC} < 5.5 V	–0.5		0.2 V_{CC}–0.1	V
		2.7 V<V_{CC}< 4.0 V	–0.5		0.7	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)		0.2 V_{CC}+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST[11]		0.7 V_{CC}		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, [8]	V_{CC} = 2.7 V I_{OL} = 1.6 mA[2]			0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$[8, 7]	V_{CC} = 2.7 V I_{OL} = 3.2 mA[2]			0.4	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 2.7 V I_{OH} = –20 µA	V_{CC} – 0.7			V
		V_{CC} = 4.5 V I_{OH} = –30 µA	V_{CC} – 0.7			V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 2.7 V I_{OH} = –3.2 mA	V_{CC} – 0.7			V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4 V	–1		–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0 V See note 4			–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3			±10	µA
I_{CC}	Power supply current (see Figure 21): Active mode @ 16 MHz Idle mode @ 16 MHz Power-down mode or clock stopped (see Figure 25 for conditions)	See note 5 T_{amb} = 0°C to 70°C T_{amb} = –40°C to +85°C		 3	 50 75	 µA µA µA µA
R_{RST}	Internal reset pull-down resistor		40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)				15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5 V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE pin may exceed 0.8 V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5 mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the V_{CC}–0.7 specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2 V.
5. See Figures 22 through 25 for I_{CC} test conditions.
   Active mode: I_{CC} = 0.9 × FREQ. + 1.1 mA
   Idle mode: I_{CC} = 0.18 × FREQ. +1.01 mA; See Figure 21.
6. This value applies to T_{amb} = 0°C to +70°C. For T_{amb} = –40°C to +85°C, I_{TL} = –750 µA.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15 mA (*NOTE: This is 85°C specification.)
   Maximum I_{OL} per 8-bit port: 26 mA
   Maximum total I_{OL} for all outputs: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25 pF. Pin capacitance of ceramic package is less than 15 pF (except $\overline{EA}$ is 25 pF).
11. To improve noise rejection a nominal 100 ns glitch rejection circuitry has been added to the RST pin, and a nominal 15 ns glitch rejection circuitry has been added to the $\overline{INT0}$ and $\overline{INT1}$ pins. Previous devices provided only an inherent 5 ns of glitch rejection.

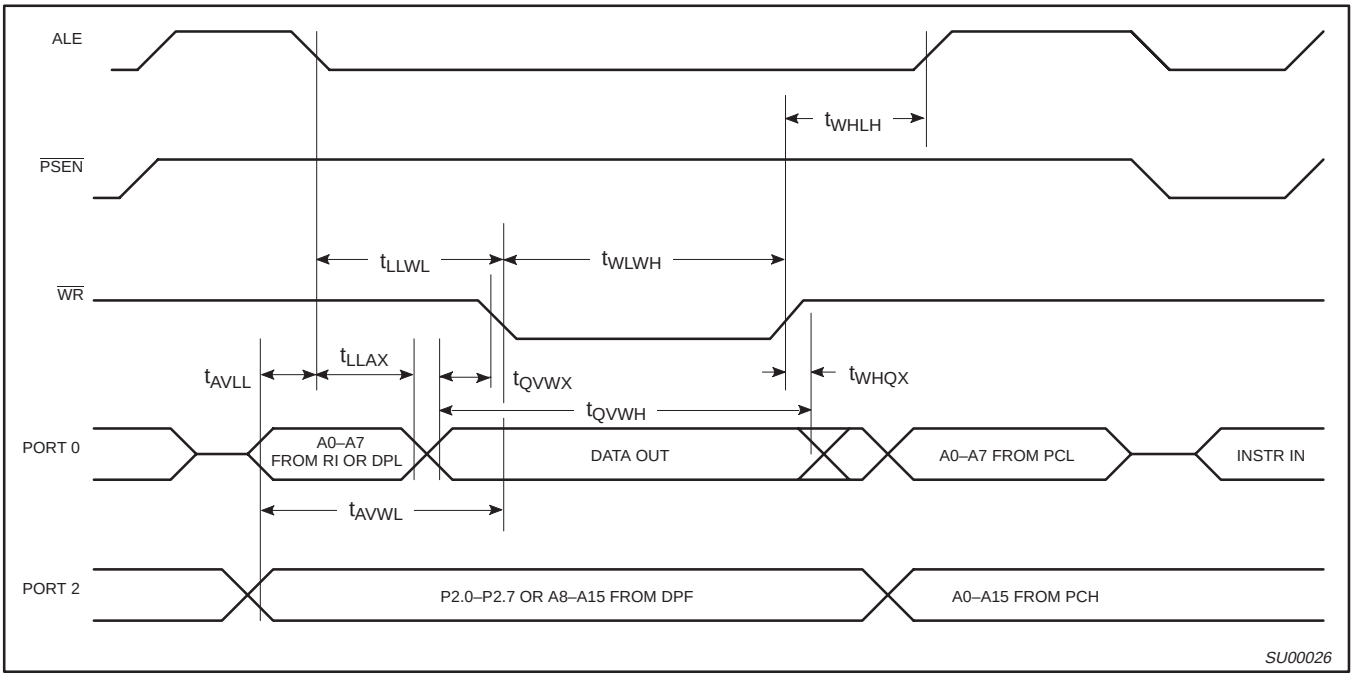


Figure 16. External Data Memory Write Cycle

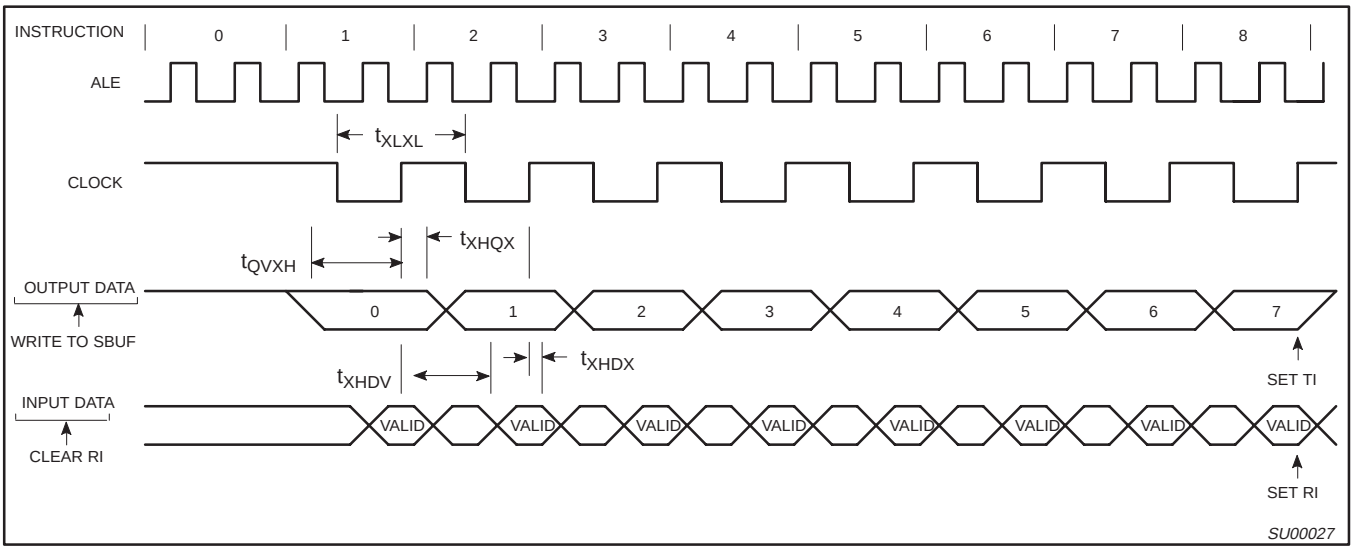


Figure 17. Shift Register Mode Timing

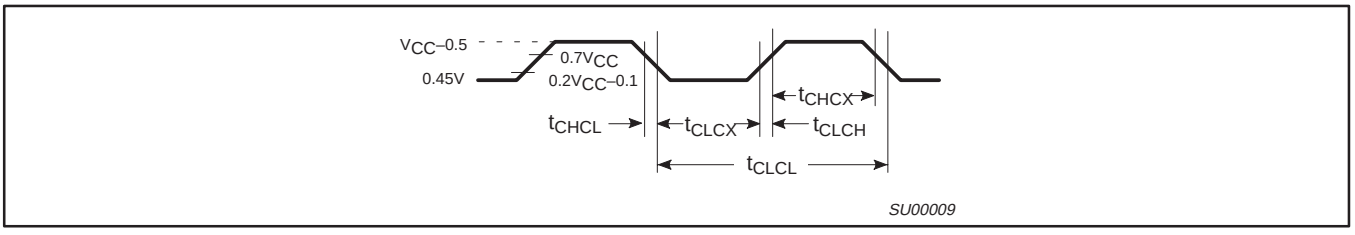


Figure 18. External Clock Drive

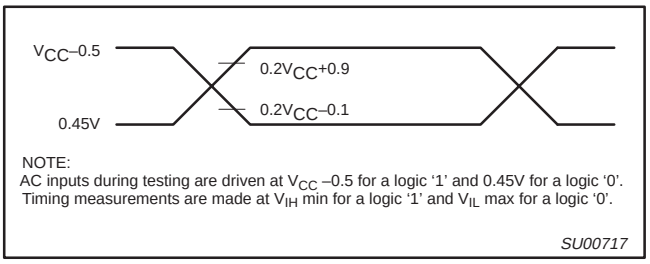


Figure 19. AC Testing Input/Output

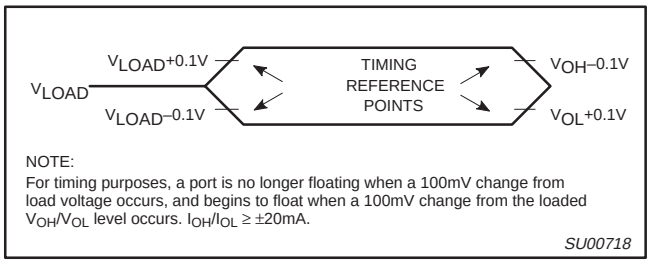


Figure 20. Float Waveform

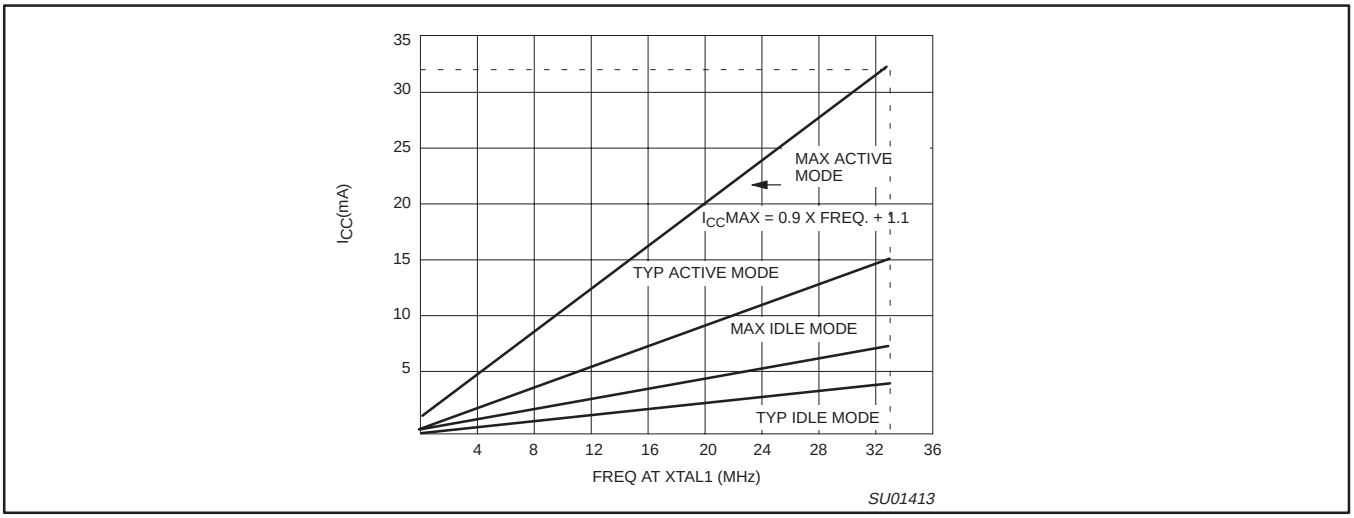


Figure 21. I_{CC} vs. FREQ
Valid only within frequency specifications of the device under test

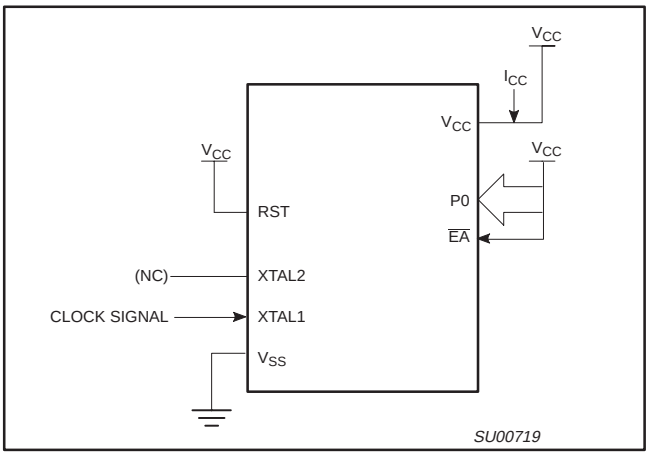


Figure 22. I_{CC} Test Condition, Active Mode
All other pins are disconnected

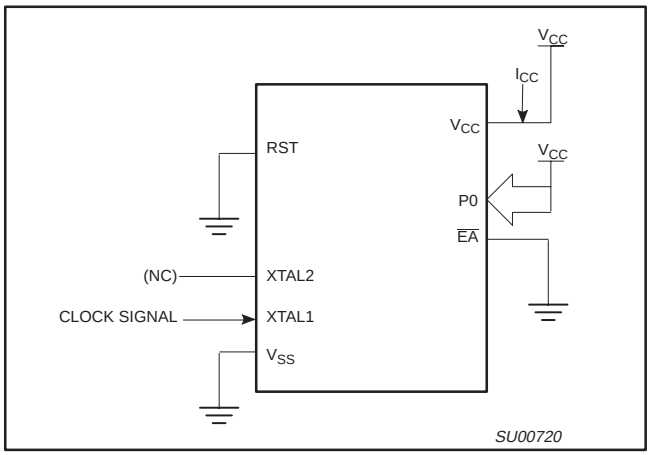


Figure 23. I_{CC} Test Condition, Idle Mode
All other pins are disconnected

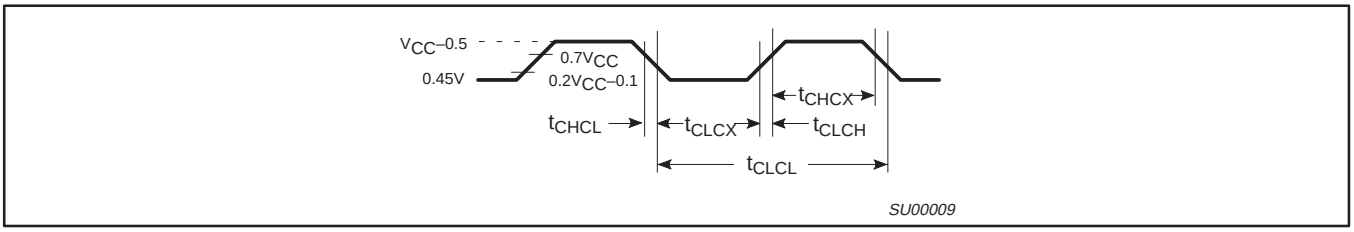


Figure 24. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes
$t_{CLCH} = t_{CHCL} = 5$ns

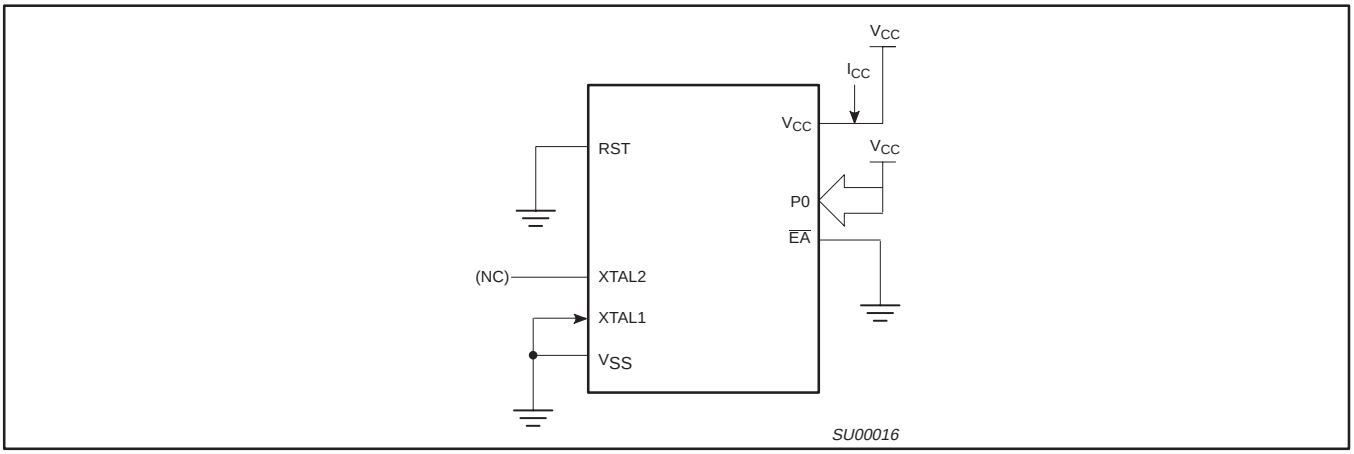


Figure 25. I_{CC} Test Condition, Power Down Mode
All other pins are disconnected. V_{CC} = 2 V to 5.5 V

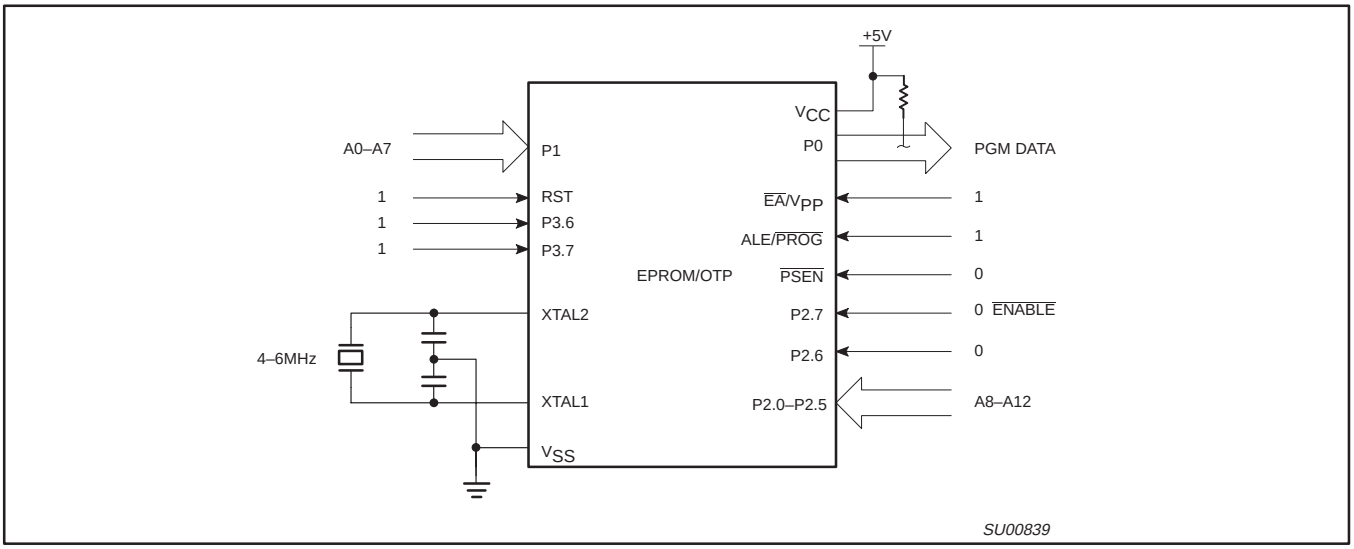


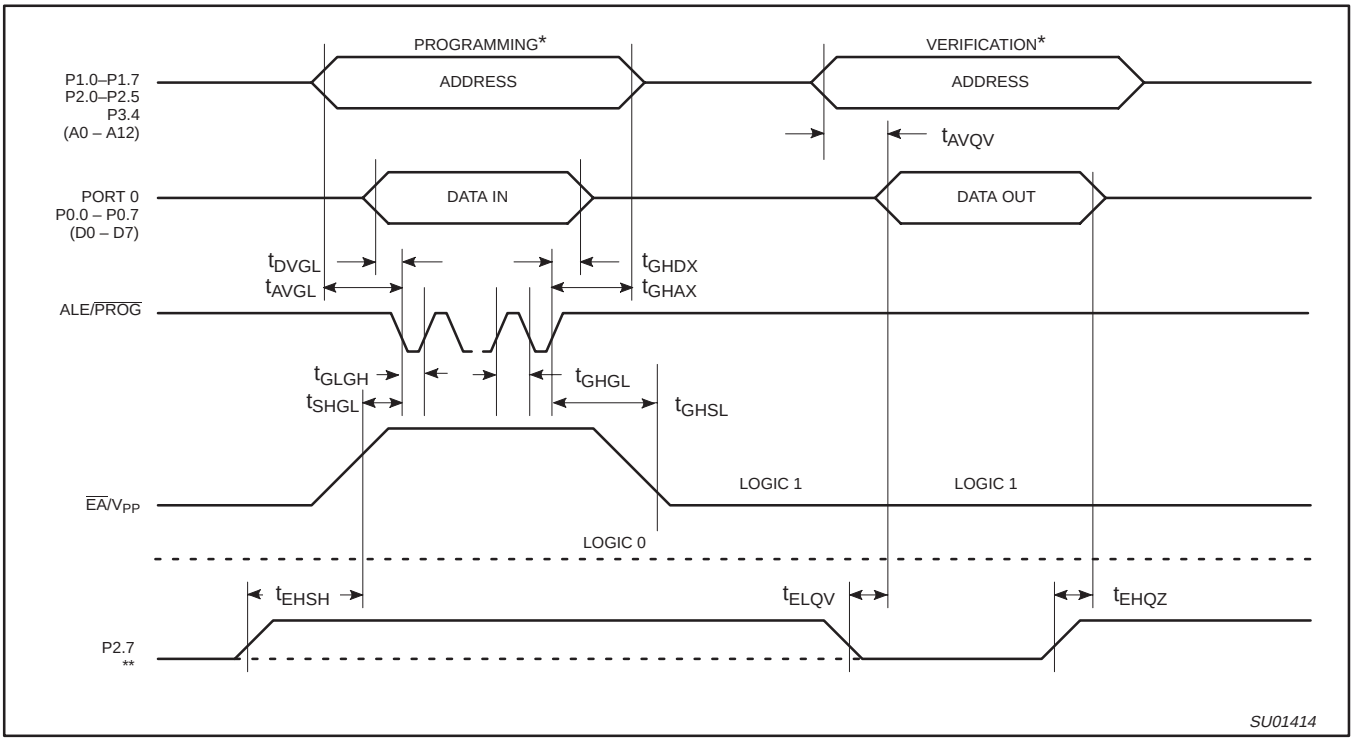
Figure 28. Program Verification

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

T_{amb} = 21°C to +27°C, V_{CC} = 5 V±10%, V_{SS} = 0 V (See Figure 29)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V_{PP}	Programming supply voltage	12.5	13.0	V
I_{PP}	Programming supply current		50 [1]	mA
$1/t_{CLCL}$	Oscillator frequency	4	6	MHz
t_{AVGL}	Address setup to $\overline{PROG}$ low	$48t_{CLCL}$		
t_{GHAX}	Address hold after $\overline{PROG}$	$48t_{CLCL}$		
t_{DVGL}	Data setup to $\overline{PROG}$ low	$48t_{CLCL}$		
t_{GHDX}	Data hold after $\overline{PROG}$	$48t_{CLCL}$		
t_{EHSH}	P2.7 ($\overline{ENABLE}$) high to V_{PP}	$48t_{CLCL}$		
t_{SHGL}	V_{PP} setup to $\overline{PROG}$ low	10		µs
t_{GHSL}	V_{PP} hold after $\overline{PROG}$	10		µs
t_{GLGH}	$\overline{PROG}$ width	90	110	µs
t_{AVQV}	Address to data valid		$48t_{CLCL}$	
t_{ELQZ}	$\overline{ENABLE}$ low to data valid		$48t_{CLCL}$	
t_{EHQZ}	Data float after $\overline{ENABLE}$	0	$48t_{CLCL}$	
t_{GHGL}	$\overline{PROG}$ high to $\overline{PROG}$ low	10		µs

NOTE:
1. Not tested.



NOTES:

* FOR PROGRAMMING CONFIGURATION SEE FIGURE 26.
FOR VERIFICATION CONDITIONS SEE FIGURE 28.

** SEE TABLE 8.

Figure 29. EPROM Programming and Verification

MASK ROM DEVICES

Security Bits

With none of the security bits programmed the code in the program memory can be verified. If the encryption table is programmed, the code will be encrypted when verified. When only security bit 1 (see Table 10) is programmed, MOVC instructions executed from external program memory are disabled from fetching code bytes from the internal memory, $\overline{EA}$ is latched on Reset and all further programming of the EPROM is disabled. When security bits 1 and 2 are programmed, in addition to the above, verify mode is disabled.

Encryption Array

64 bytes of encryption array are initially unprogrammed (all 1s).

Table 10. Program Security Bits

PROGRAM LOCK BITS[1, 2]			
	SB1	SB2	PROTECTION DESCRIPTION
1	U	U	No Program Security features enabled. (Code verify will still be encrypted by the Encryption Array if programmed.)
2	P	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on Reset, and further programming of the EPROM is disabled.

NOTES:

1. P – programmed. U – unprogrammed.
2. Any other combination of the security bits is not defined.

80C51 ROM CODE SUBMISSION

When submitting ROM code for the 80C51, the following must be specified:

1. 4k byte user ROM data
2. 64 byte ROM encryption key
3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 0FFFH	DATA	7:0	User ROM Data
1000H to 103FH	KEY	7:0	ROM Encryption Key
1040H	SEC	0	ROM Security Bit 1
1040H	SEC	1	ROM Security Bit 2

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

1. External MOVC is disabled, and
2. $\overline{EA}$ is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

NOTE: Security Bit 2 cannot be enabled unless Security Bit 1 is enabled.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1: ☐ Enabled ☐ Disabled

Security Bit #2: ☐ Enabled ☐ Disabled

Encryption: ☐ No ☐ Yes If Yes, must send key file.

80C52 ROM CODE SUBMISSION

When submitting ROM code for the 80C52, the following must be specified:

1. 8k byte user ROM data
2. 64 byte ROM encryption key
3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 1FFFH	DATA	7:0	User ROM Data
2000H to 203FH	KEY	7:0	ROM Encryption Key
2040H	SEC	0	ROM Security Bit 1
2040H	SEC	1	ROM Security Bit 2

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

1. External MOVC is disabled, and
2. $\overline{EA}$ is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

NOTE: Security Bit 2 cannot be enabled unless Security Bit 1 is enabled.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

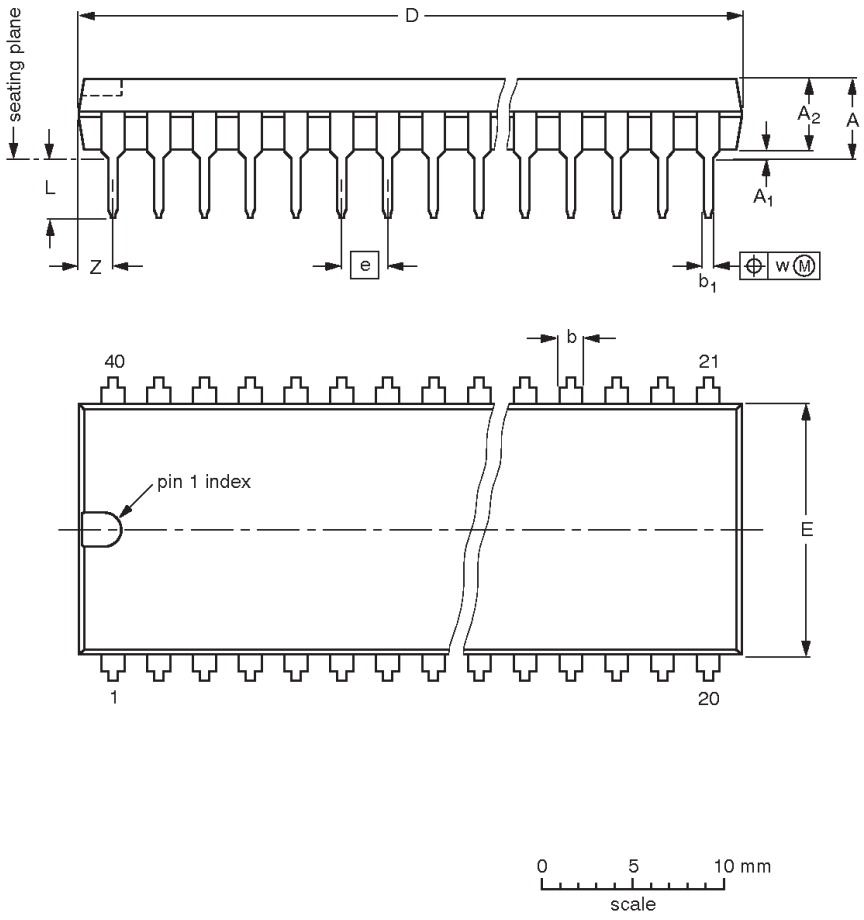
For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1: ☐ Enabled ☐ Disabled

Security Bit #2: ☐ Enabled ☐ Disabled

Encryption: ☐ No ☐ Yes If Yes, must send key file.

DIP40: plastic dual in-line package; 40 leads (600 mil) SOT129-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

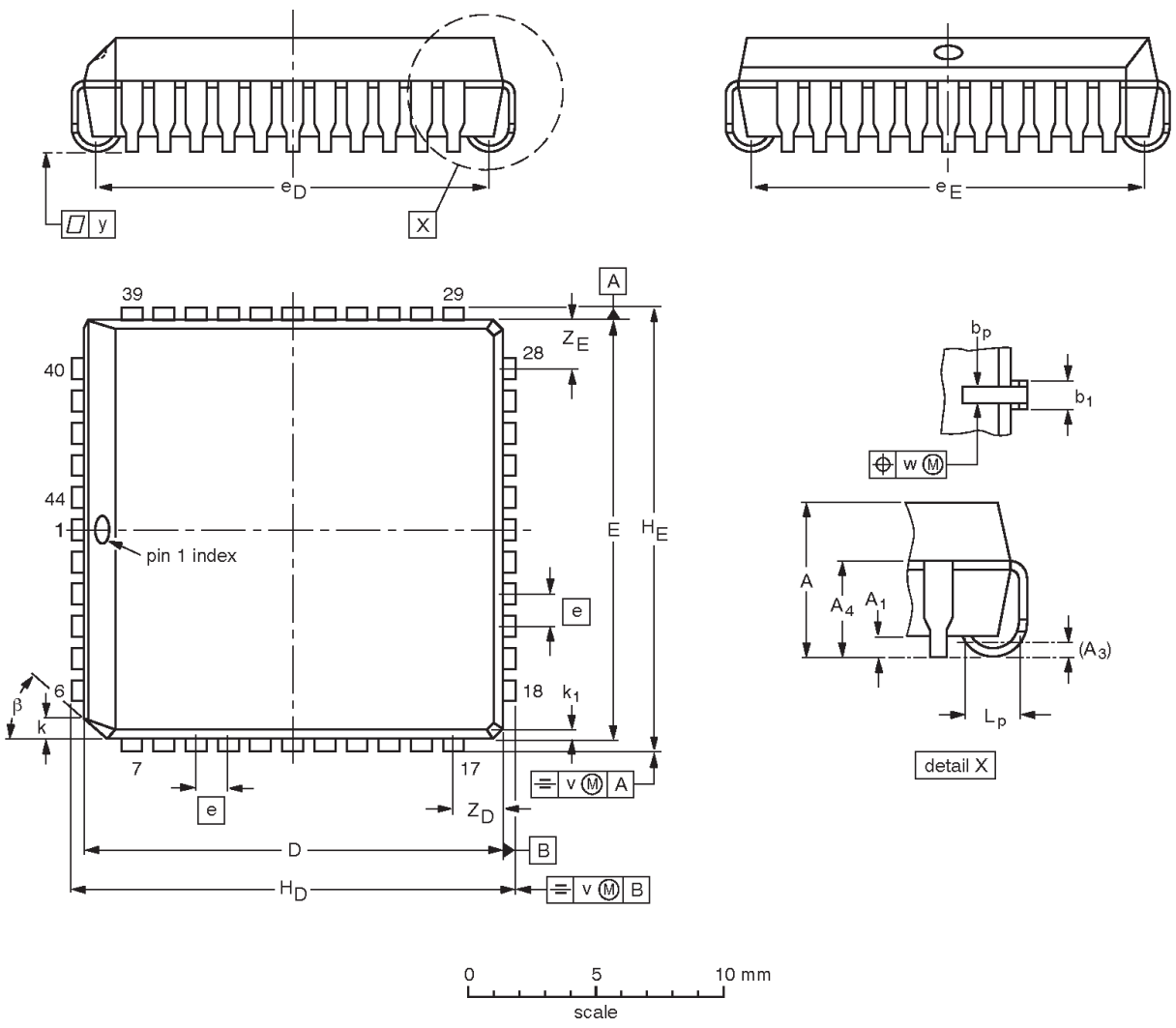
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT129-1	051G08	MO-015	SC-511-40			~~95-01-14~~ 99-12-27

PLCC44: plastic leaded chip carrier; 44 leads SOT187-2



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	k_1 max.	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	16.66 16.51	16.66 16.51	1.27	16.00 14.99	16.00 14.99	17.65 17.40	17.65 17.40	1.22 1.07	0.51	1.44 1.02	0.18	0.18	0.10	2.16	2.16	45^o
inches	0.180 0.165	0.020	0.01	0.12	0.021 0.013	0.032 0.026	0.656 0.650	0.656 0.650	0.05	0.630 0.590	0.630 0.590	0.695 0.685	0.695 0.685	0.048 0.042	0.020	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT187-2	112E10	MO-047				~~97-12-16~~ 99-12-27

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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